COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

EARPHONE STRUCTURE WITH A COMPOSITE SOUND FIELD

the	specification of w	hich 'hich			
_ <u>X</u>	is attached here was filed on as Application S		nd was amended on		
app fore any app	ecification, including acknowledge blication in accordation in accordation accordation (s) foreign application application (s)	ng the claims, as ament the duty to disclose in ance with Title 37, Cod foreign priority benef for patent or inventor on for patent or inver priority is claimed:	and understood the content aded by any amendment refer- aformation which is material to the of Federal Regulations, § 1 tits under Title 35, United States its certificate listed below and antor's certificate having a filin	red to above. o the patental 1.56(a). ates Code, § have also ide	bility of this 119 of any ntified below
	Number	Country	Date Filed(yyyy/mm/dd)	Yes	No
	93111985	Taiwan, R.O.C.	2004/04/14	X	
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SEND CORRESPONDENCE TO:

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COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature:

Date:

04/23/2004

Sole or First Joint Inventor: Bill Yang

Citizenship: Taiwan, R.O.C.

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